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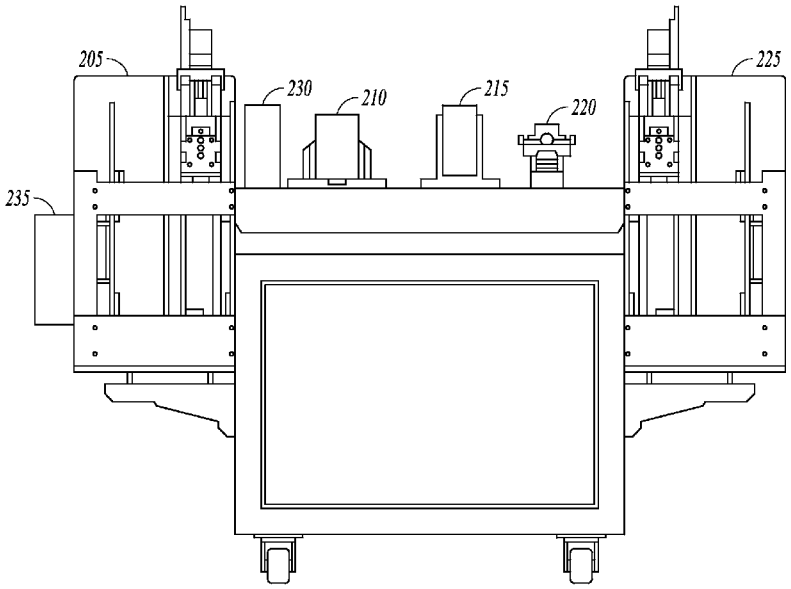

FIG. 2

(57) Abstract: An apparatus comprises a wire bonder system including a wire bonding device (210), a measuring device (215) and a rejection device (220). The wire bonding device (210) is configured to attach wire bond type electrical interconnect to an electronic assembly. A wire bond is formed between a first semiconductor device and a second electronic device to form at least a portion of the electronic assembly. The measuring device (215) is configured to perform a three dimensional measurement associated with a wire bond, and the rejection device (220) is configured to identify an electronic assembly for rejection according to the three dimensional wire bond measurement.

WO 2015/088658 A3